

CONTENTS

Declaration	i
Preface	ii
Acknowledgement	iii
Abstract	iv
1 Introduction	1
1.1 The Semiconductor Industry	1
1.2 The Hermetic Package Assembly Process	4
1.3 Die Attach Process	12
1.4 Die Attach Materials	14
1.4.1 Direct Materials	14
1.4.2 Indirect Materials	15
1.5 Die Attach Defects	18
1.5.1 Present Defect Levels	18
1.5.2 Present Accepted Criteria	20
1.6 About This Report	20
2 Experimental Techniques	24
2.1 Categorization Of FM Defects	24
2.2 FM Mapping	25
2.3 Simulation Of FM Rejects	29
2.4 Material Analysis	29
2.4.1 Elemental Analysis	30
2.4.2 Depth Analysis	32

3.4	Material Analysis	64
3.4.1	Elemental Analysis	64
3.4.2	Depth Analysis	70
3.5	Electrical Analysis	72
3.5.1	Lead-To-Lead electrical measurements	72
4	Functional Testing Results And Discussion	74
4.1	Functional Testing	74
4.2	Failure And FM Location Correlation	76
4.3	Reliability Testing	77
4.3.1	Functional Reliability Testing	77
4.3.2	Failure and FM Location Correlation	78
4.3.3	PIND Test	78
5	Conclusion and Suggestion For Further Work	80
5.1	Conclusion	80
5.2	FM Reject Criteria Relaxation	81
5.3	Suggestions for Further Work	84
References	85	
Appendix A	87	
Appendix B	108	